

Response  
Serial No. 10/763,267  
Attorney Docket No. 042057

**AMENDMENTS TO THE SPECIFICATION**

Please amend the specification as follows:

**Amend the paragraph beginning on page 6, line 16 as follows:**

Fig. 1 shows a stacked semiconductor device (henceforth referred to as “semiconductor device”) 10A according to the first embodiment of the present invention. The semiconductor device 10A includes an upper semiconductor device unit 11A (henceforth called “upper device unit”), a lower semiconductor device unit 12A (henceforth called “lower device unit”), and an interposer substrate 13A, ~~which interposer substrate 13A represents the third wiring substrate given in claim 3 of the present invention.~~